



Tentative Specification
<b>Preliminary Specification</b>
Approval Specification

# MODEL NO.: G150XNE SUFFIX: L02

Customer:	
APPROVED BY	SIGNATURE
Name / Title Note	^
Please return 1 copy for you signature and comments.	ır confirmation with your

Approved By	Checked By	Prepared By

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### **REVISION HISTORY**

Version	Date	Page	Description
Ver 0.0	14 Dec 2018	All	Tentative Specification was first issued.
Ver 0.1	25 Jan 2019	5	1.4 Module Power Consumption updated.
		9	3.1 Power Supply Current Value updated.
		10	3.2 Backlight Unit Parameter updated.
		14	5.1 Pin#4 Function Description modified.

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#### 1. GENERAL DESCRIPTION

#### 1.1 OVERVIEW

G150XNE-L02 is a 15.0" TFT Liquid Crystal Display IAV module with LED Backlight units and 20 pins LVDS interface. This module supports 1024 x 768 XGA mode and can display 16.2M/262k colors.

The PSWG is to establish a set of displays with standard mechanical dimensions and select electrical interface requirements for an industry standard 15.0" XGA LCD panel and the LED driving device for Backlight is built in PCBA.

#### **1.2 FEATURE**

- XGA (1024 x 768 pixels) resolution
- DE (Data Enable) only mode
- LVDS Interface with 1pixel/clock
- PSWG (Panel Standardization Working Group)
- Wide operating temperature.
- RoHS compliance

#### 1.3 APPLICATION

- -TFT LCD Monitor
- Factory Application
- Amusement

#### 1.4 GENERAL SPECIFICATIONS

Item	Specification	Unit	Note
Active Area	304.1 (H) x 228.1(V) (15.0" diagonal)	mm	(1)
Bezel Opening Area	307.4(H) x 231.3(V)	mm	(1)
Driver Element	a-Si TFT active matrix	-	-
Pixel Number	1024 x R.G.B x 768	pixel	-
Pixel Pitch	0.297(H) x 0.297(W)	mm	-
Pixel Arrangement	RGB vertical Stripe	-	-
Display Colors	16.2M / 262K	color	-
Display Mode	Normally Black / VA	-	-
Surface Treatment	Hard Coating (3H), Anti-Glare	-	-
Module Power Consumption	7.9	W	Max.



#### 1.5 MECHANICAL SPECIFICATIONS

Item		Min.	Тур.	Max.	Unit	Note
	Horizontal(H)	326.0	326.5	327.0	mm	(1)
Module Size	Vertical(V)	253.0	253.5	254.0	mm	(1)
	Depth(D)	8.6	9.1	9.6	mm	(1)(2)
Bezel Area	Horizontal	307.1	307.4	307.7	mm	-
bezei Alea	Vertical	231.0	231.3	231.6	mm	
Active Area	Horizontal	-	304.1	-	mm	
Active Area	Vertical	-	228.1	-	mm	
Weight		-	960	1000	g	

Note (1)Please refer to the attached drawings for more information of front and back outline dimensions.

Note (2) The depth is without connector.





#### 2. ABSOLUTE MAXIMUM RATINGS

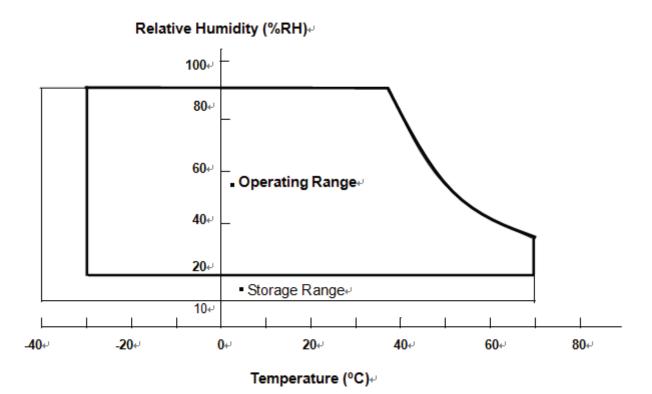
#### 2.1 ABSOLUTE RATINGS OF ENVIRONMENT

Item	Symbol	Va	lue	Unit	Note	
iteiii	Syllibol	Min.	Max.	Offic		
Operating Ambient Temperature	T <sub>OP</sub>	-30	+70	$^{\circ}\mathbb{C}$	(1)(2)(3)	
Storage Temperature	$T_{ST}$	-40	+70	$^{\circ}\!\mathbb{C}$	(1)(2)(3)	

Note (1) Temperature and relative humidity range is shown in the figure below.

Note (2) 90 %RH Max. (Ta <  $40^{\circ}$ C).

Note (3) Wet-bulb temperature should be 39°C Max.





#### 2.2 ELECTRICAL ABSOLUTE RATINGS

#### 2.2.1 TFT LCD MODULE

Item	Symbol	Value		Unit	Note	
item	Symbol	Min.	Max.	Offic	Note	
Power Supply Voltage	VCC	-0.3	4	V	(1)	

#### 2.2.2 BACKLIGHT UNIT

Item	Symbol	Va	lue	Unit	Note	
item	Symbol	Min.	Max.	Offic	Note	
Converter Voltage	Vi	-0.3	18	V	(1), (2)	
Enable Voltage	EN		5.5	V		
Backlight Adjust	Dimming		5.5	V	<u> </u>	

Note (1) Permanent damage to the device may occur if maximum values are exceeded. Function operation should be restricted to the conditions described under Normal Operating Conditions.

Note (2) Specified values are for lamp (Refer to 3.2 for further information).



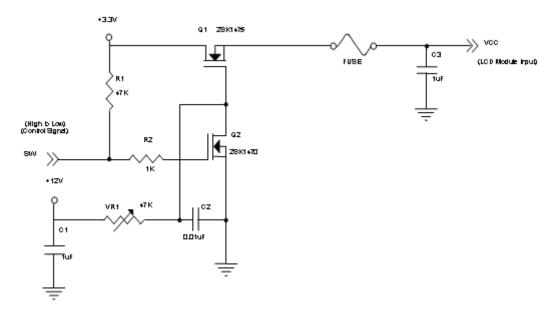
#### 3. ELECTRICAL CHARACTERISTICS

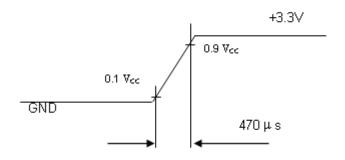
#### 3.1 TFT LCD MODULE

Parameter	Symbol		Value	Unit	Note		
Farameter	Symbol	Min.	Тур.	Max.	Offic	Note	
Power Supply Vo	Itage	V <sub>CC</sub>	3.0	3.3	3.6	V	-
Ripple Voltag	е	$V_{RP}$	ı	ı	100	mVp-p	
Rush Current		I <sub>RUSH</sub>	ı	ı	2.0	Α	(2)
Power Supply Current	White	lcc	ı	455	545	mA	(3)a
Fower Supply Current	Black	ICC	-	350	420	mA	(3)b
LVDS differential inpu	ıt voltage	Vid	200	-	600	mV	
LVDS common input	voltage	Vic	1.0	1.2	1.4	V	
Differential Input Voltage for	"H" Level	V <sub>IH</sub>	1	1	100	mV	-
LVDS Receiver Threshold	"L" Level	$V_{IL}$	-100	-	-	mV	-
Terminating Res	istor	R <sub>T</sub>	-	100	-	Ohm	-

Note (1)The module should be always operated within above ranges.

Note (2)Measurement Conditions:

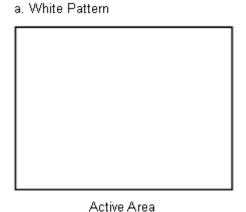




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Note (3) The specified power supply current is under the conditions at  $V_{DD}$  =3.3V, Ta = 25 ± 2  $^{\circ}$ C, DC Current and  $f_v$  = 60 Hz, whereas a power dissipation check pattern below is displayed.



b. Black Pattern



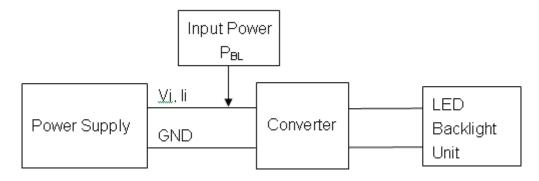
Active Area

#### 3.2 BACKLIGHT UNIT

Ta = 25 ± 2 °C

Paramete	\#	Cymbol		Value	Unit	Note	
Paramete	<del>)</del> I	Symbol	Min.	Тур.	Max.	Unit	Note
Converter Power Su	pply Voltage	$V_{i}$	10.8	12.0	13.2	V	
Converter Power Su	l <sub>i</sub>	0.4	0.5	0.6	А	@ Vi = 12V (Duty 100% For Vf 3.05Vmax)	
Backlight Power Co	$P_{BL}$	ı	6	6.1	W	@ Vi = 12V (Duty 100%)	
EN Control Level	Backlight on		2.0	3.3	5.0	V	
EN Control Level	Backlight off	-	0	-	0.15	V	
PWM Dimming Control	PWM High Level		2.0	3.3	5.0	V	
Level	PWM Low Level	-	0	-	0.15	V	
PWM Dimming Contr	-	1	-	100	%	@200Hz	
PWM Dimming Contr	$f_{PWM}$	190	200	20k	Hz	(2)	
LED Life Ti	me	LL	50,000	70,000	-	Hrs	(3)

Note (1)LED current is measured by utilizing a high frequency current meter as shown below:



Note (2) At 20k Hz PWM control frequency, duty ratio range is restricted from 20% to 100%.

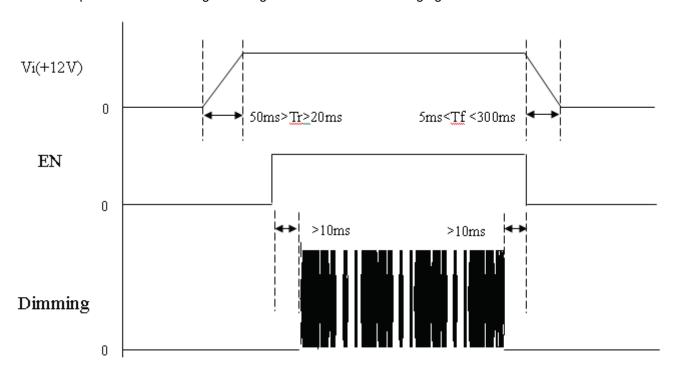
Note (3) The lifetime of LED is estimated data and defined as the time when it continues to operate under the conditions at  $Ta = 25 \pm 2$  °C and Duty 100% until the brightness becomes  $\leq 50$ % of its



original value. Operating LED under high temperature environment will reduce life time and lead to color shift.



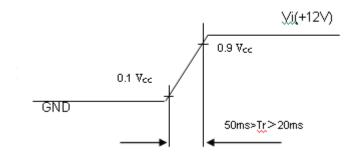
Power sequence and control signal timing are shown in the following figure



Note: While system is turned ON or OFF, the power sequences must follow as below descriptions

Turn ON sequence:  $Vi(+12V) \rightarrow EN \rightarrow Dimming$ Turn OFF sequence: Dimming  $\rightarrow EN \rightarrow Vi(+12V)$ 

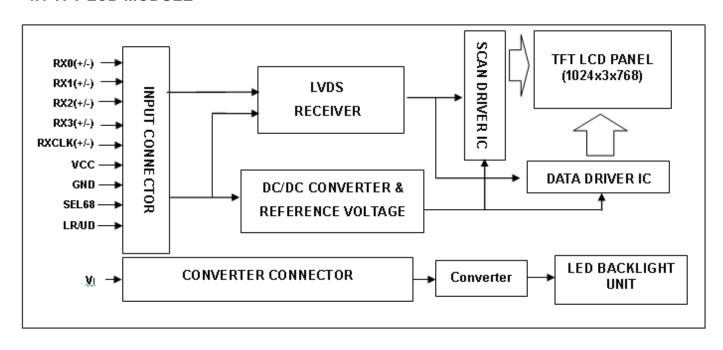
Note (4)





#### 4. BLOCK DIAGRAM

#### 4.1 TFT LCD MODULE





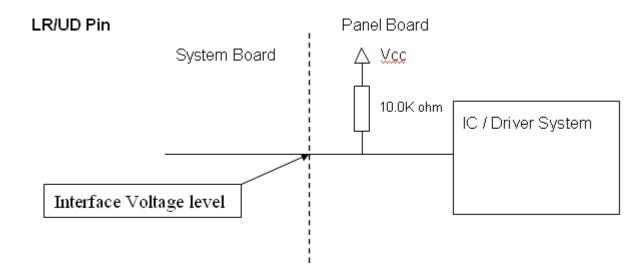


#### 5. INPUT TERMINAL PIN ASSIGNMENT

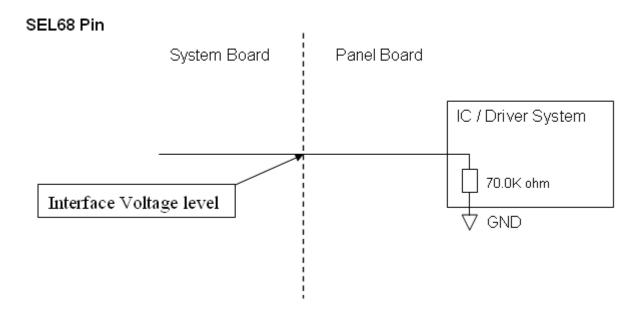
#### **5.1 TFT LCD MODULE**

Pin No.	Symbol	Function	Polarity	Note
1	VCC	Power Supply +3.3V(typical)		
2	VCC	Power Supply +3.3V(typical)		
3	NC	No Connection (Reserve for INX test)		Note (4)
4	NC	No Connection (Reserve for INX test)		Note (3)
5	RX0-	LVDS Differential Data Input	Negative	
6	RX0+	LVDS Differential Data Input	Positive	
7	GND	Ground		
8	RX1-	LVDS Differential Data Input	Negative	
9	RX1+	LVDS Differential Data Input	Positive	
10	NC	No Connection (Reserve for INX test)		Note (4)
11	RX2-	LVDS Differential Data Input	Negative	,
12	RX2+	LVDS Differential Data Input	Positive	
13	GND	Ground		
14	RXCLK-	LVDS Differential Data Input	Negative	
15	RXCLK+	LVDS Differential Data Input	Positive	
16	GND	Ground		
17	RX3-	LVDS Differential Data Input	Negative	
18	RX3+	LVDS Differential Data Input	Positive	
19	NC	No Connection (Reserve for INX test)		Note (4)
20	SEL68	LVDS 6/8 bit select function control,		Note (3)
		High → 6bit Input Mode		
		Low or NC → 8bit Input Mode		

- Note (1) Connector Part No.: Cvilux CID520D1HR0-NH or equivalent.
- Note (2) User's connector Part No.: Hirose DF14-20S-1.25C or equivalent.
- Note (3) "Low" stands for 0V. "High" stands for 3.3V. "NC" stands for "No Connection".
- Note (4) Pin3, Pin10, Pin19 input signals should be set to no connection or ground, this module would operate normally.





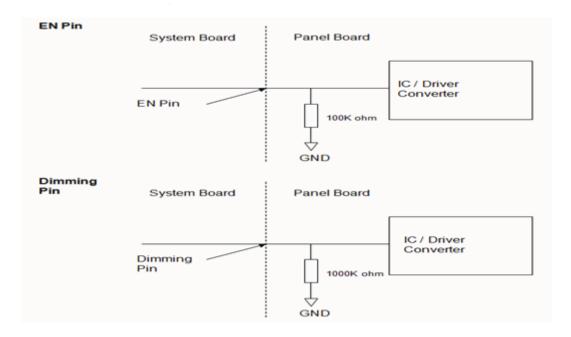


#### 5.2 BACKLIGHT UNIT(Converter connector pin)

Pin	Symbol	Description	Remark
1	V <sub>i</sub>	Converter input voltage	12V
2	$V_{GND}$	Converter ground	Ground
3	EN	Enable pin	3.3V
4	Dimming	Backlight Adjust	PWM Dimming (Hi: 3.3V <sub>DC</sub> , Lo: 0V <sub>DC</sub> )
5	NC	Not Connect	

Note (1)Connector Part No.: CI4205M2HRP-NH (Cvilux) or equivalent.

Note (2)User's connector Part No.: CI4205SL000 (Cvilux) or equivalent.





#### **5.3 COLOR DATA INPUT ASSIGNMENT**

The brightness of each primary color (red, green and blue) is based on the 8-bit gray scale data input for the color. The higher the binary input the brighter the color. The table below provides the assignment of color versus data input.

												D	ata	Sig	nal										
	Color				Re								Gre	een								ue			
		R7	R6	R5	R4	R3	R2	R1	R0	G7	G6	G5	G4	G3	G2	G1	G0	В7	B6	B5	B4	В3	B2	B1	B0
	Black	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Green	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
Basic	Blue	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1
Colors	Cyan	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
	Magenta	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1
	Yellow	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
	White	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
	Red(0) / Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red(1)	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Gray	Red(2)	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Scale	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Of	:	:	:		:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Red	Red(252)	1	1	1	1	1	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
1 (Gu	Red(252)	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red(252)	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Green(0)/Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Green(1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0
Gray	Green(2)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0
Scale	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Of	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Green	Green(252)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	0	1	0	0	0	0	0	0	0	0
Oreen	Green(252)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0
	Green(252)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
	Blue(0) / Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Blue(1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1
Gray	Blue(2)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0
Scale	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Of	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Blue	Blue(252)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	0	1
Dide	Blue(252)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0
	Blue(252)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1

Note (1)0: Low Level Voltage, 1: High Level Voltage



#### 6. INTERFACE TIMING

#### **6.1 INPUT SIGNAL TIMING SPECIFICATIONS**

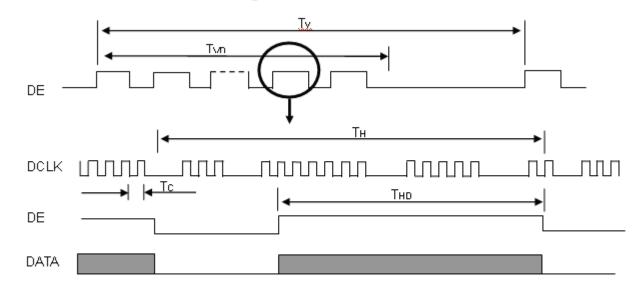
The input signal timing specifications are shown as the following table and timing diagram.

Signal	Item	Symbol	Min.	Тур.	Max.	Unit	Note
	Frequency	Fc	53.35	65	80	MHz	-
	Period	Tc	12.5	15.38	18.75	ns	
	Input cycle to cycle jitter	T <sub>rcl</sub>			200	ns	(a)
LVDS Clock	Input Clock to data skew	TLVCCS	-0.02*Tc	ı	0.02*Tc	ps	(b)
	Spread spectrum modulation range	F <sub>clkin_mod</sub>	ı	ı	1.02*Fc	MHz	(0)
	Spread spectrum modulation frequency	F <sub>SSM</sub>	ı	ı	200	KHz	(c)
	Frame Rate	Fr	55	60	70	Hz⊸	Tv=Tvd+Tvb
Vertical Display	Total	Tv	780	806	840	Th	ı
Term	Active Display	Tvd	768	768	768	Th	-
	Blank	Tvb	Tv-Tvd	38	Tv-Tvd	70 Hz Tv 840 Th 768 Th Tv-Tvd Th 1360 Tc Th	-
	Total	Th	1240	1344	1360	Tc	Th=Thd+Thb
Horizontal Display Term	Active Display	Thd	1024	1024	1024	Tc	-
161111	Blank	Thb	Th-Thd	320	Th-Thd	Tc	-

Note (1) Because this module is operated by DE only mode, Hsync and Vsync input signals should be set to low logic level or ground. Otherwise, this module would operate abnormally.

Note (2) The Tv(Tvd+Tvb) must be integer, otherwise, the module would operate abnormally.

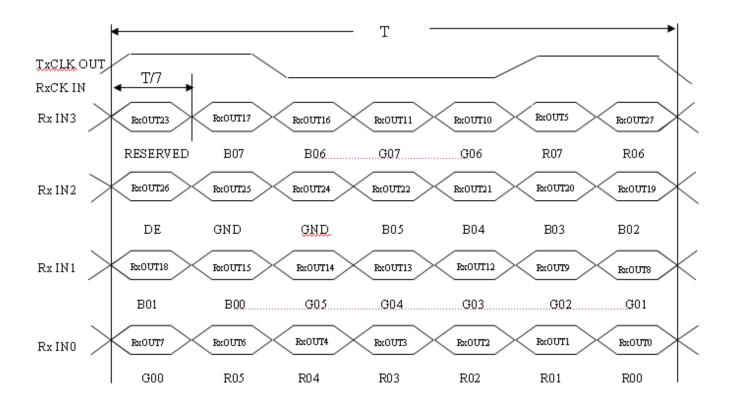
#### **INPUT SIGNAL TIMING DIAGRAM**



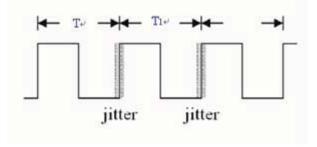
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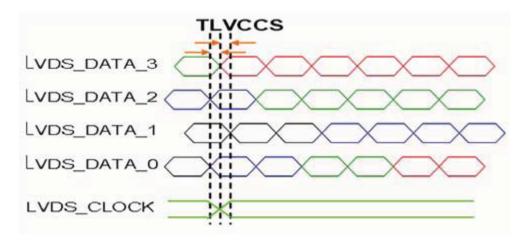
#### **TIMING DIAGRAM of LVDS**



Note (a) The input clock cycle-to-cycle jitter is defined as below figures. Trcl = I T1 – TI

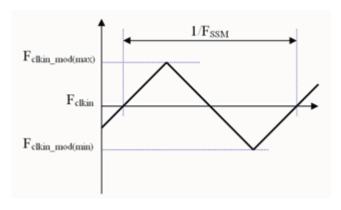


Note (b) Input Clock to data skew is defined as below figures.



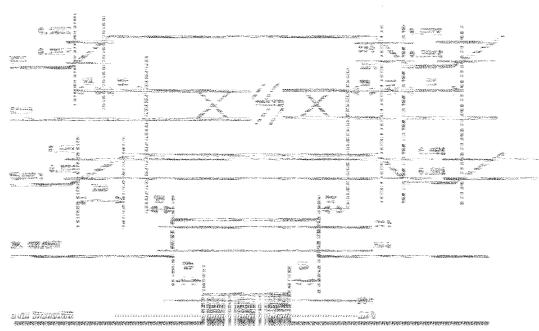


Note (c) The SSCG (Spread spectrum clock generator) is defined as below figures.



#### **6.2 POWER ON/OFF SEQUENCE**

To prevent a latch-up or DC operation of LCD assembly, the power on/off sequence should be as the diagram below.



#### Power ON/OFF sequence

- Note (1) Please avoid floating state of interface signal at invalid period.
- Note (2) When the interface signal is invalid, be sure to pull down the power supply of LCD VCC to 0 V.
- Note (3) The Backlight converter power must be turned on after the power supply for the logic and the interface signal is valid. The Backlight converter power must be turned off before the power supply for the logic and the interface signal is invalid.

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Parameter		Units				
Parameter	Min	Тур	Max	Offics		
T1	0.5	1	10	ms		
T2	0	1	50	ms		
Т3	0	1	50	ms		
T4	500	1	-	ms		
T5	450	1	-	ms		
T6	200	1	-	ms		
Т7	10	1	100	ms		
Т8	10	1	-	ms		
Т9	10	1	-	ms		
T10	20		50	ms		

#### **6.3 SCANNING DIRECTION**

The following figures show the image see from the front view. The arrow indicates the direction of scan.

Fig.1 Normal Scan



Fig.2 Reverse Scan



- Fig. 1 Normal scan (pin 4, LR/UD = High or NC)
- Fig. 2 Reverse scan (pin 4, LR/UD = Low)



#### 7. OPTICAL CHARACTERISTICS

#### 7.1 TEST CONDITIONS

Item	Value	Unit		
Ambient Temperature (Ta)	25±2	$^{\circ}\! \mathbb{C}$		
Ambient Humidity (Ha)	50±10	%RH		
Supply Voltage	According to typical value in "ELECTRICAL CHARACTERISTICS"			
Input Signal				
LED Light Bar Input Current Per Input Pin	011	AINOTERIOTIOS		

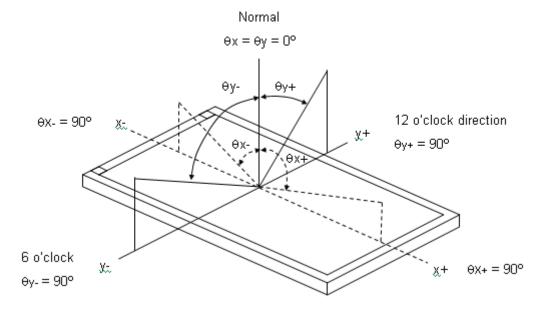
#### 7.2 OPTICAL SPECIFICATIONS

The relative measurement methods of optical characteristics are shown in 7.2 and all items are measured at the center point of screen except white variation. The following items should be measured under the test conditions described in 7.1 and stable environment shown in Note (5).

Iter	n	Symbol	Condition	Min.	Тур.	Max.	Unit	Note	
	Red	Rx			0.647				
	Neu	Ry			0.338				
	Green	Gx			0.321				
Color	Green	Gy		Тур -	0.606	Тур+	_	(1), (5)	
Chromaticity	Blue	Bx	$\theta_x=0^\circ, \ \theta_Y=0^\circ$	0.05	0.157	0.05	_	(1), (3)	
	blue	Ву	CS-1000T		0.039				
	White	Wx			0.313				
	vviiite	Wy			0.329				
Center Lumina	nce of White	L <sub>C</sub>		280	350		cd/m <sup>2</sup>	(4), (5)	
Contrast	Ratio	CR		1800	2500		-	(2), (5)	
Respons	a Tima	$T_R$	$\theta_x=0^\circ, \ \theta_Y=0^\circ$	-	16	21	ms	(3)	
Respons	e mine	$T_F$	$\theta_X = 0$ , $\theta_Y = 0$	-	7	14	1113	(3)	
White Va	ariation	δW	$\theta_x$ =0°, $\theta_Y$ =0° USB2000	-	1.25	1.33	-	(5), (6)	
	Horizontal	$\theta_x$ +		80	88	1			
Viewing Angle	Tionzontal	$\theta_{x}$ -	$CR \ge 10$	80	88	-	Dog	(1) (5)	
viewing Angle	Vertical	θ <sub>Y</sub> +	USB2000	80	88	-	Deg.	(1), (5)	
	vertical	θ <sub>Y</sub> -		80	88	-			



Note (1)Definition of Viewing Angle ( $\theta x$ ,  $\theta y$ ):



Note (2)Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression.

Contrast Ratio (CR) = L255 / L0

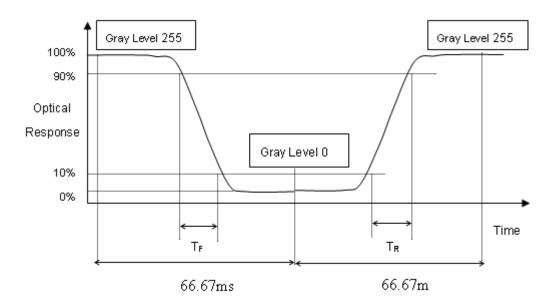
L255: Luminance of gray level 255

L0: Luminance of gray level 0

CR = CR(5)

CR (X) is corresponding to the Contrast Ratio of the point X at Figure in Note (6).

Note (3)Definition of Response Time (TR, TF):







Note (4) Definition of Luminance of White (L<sub>C</sub>):

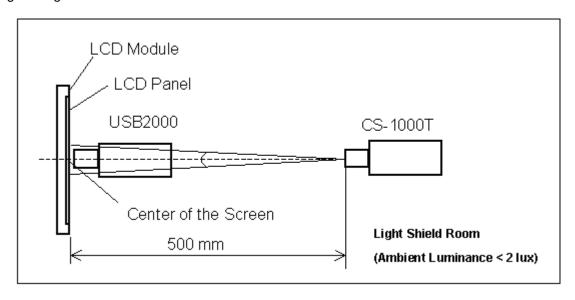
Measure the luminance of gray level 255 at center point

$$LC = L(5)$$

L(x) is corresponding to the luminance of the point X at Figure in Note (6).

#### Note (5) Measurement Setup:

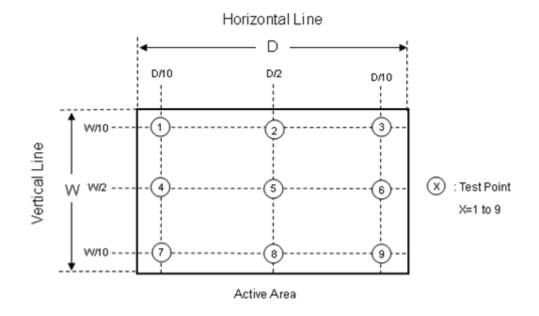
The LCD module should be stabilized at given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 20 minutes in a windless room.



Note (6) Definition of White Variation ( $\delta W$ ):

Measure the luminance of gray level 63 (255) at 9 points

$$\delta W = \frac{\text{Maximum [L (1), L (2), L (3), L (4), L (5), L (6), L (7), L (8), L (9)]}}{\text{Minimum [L (1), L (2), L (3), L (4), L (5), L (6), L (7), L (8), L (9)]}}$$



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#### 8. RELIABILITY TEST CRITERIA

Test Item	Test Condition	Note
High Temperature Storage Test	70℃, 240 hours	
Low Temperature Storage Test	-40°C, 240 hours	(4) (0)
Thermal Shock Storage Test	-30°C, 0.5 hour ←→70°C, 0.5 hour; 100cycles, 1 hour/cycle)	(1),(2) (4),(5)
High Temperature Operation Test	70℃, 240 hours	(4),(3)
Low Temperature Operation Test	-30°C, 240 hours	
High Temperature & High Humidity Operation Test	60℃, RH 90%, 240 hours	(1),(2) (4),(6)
	150pF, 330 Ω , 1 sec/cycle	
ESD Test (Operation)	Condition 1 : panel contact, ±8 KV	(1), (4)
	Condition 2 : panel non-contact ±15 KV	
Shock (Non-Operating)	50G, 11ms, half sine wave, 1 time for ± X, ± Y, ± Z direction	(2), (3)
Vibration (Non-Operating)	1.5G, 10 ~ 300 Hz sine wave, 10 min/cycle, 3 cycles each X, Y, Z direction	(2), (3)

- Note (1) There should be no condensation on the surface of panel during test.
- Note (2) Temperature of panel display surface area should be 85°C Max.
- Note (3) At testing Vibration and Shock, the fixture in holding the module has to be hard and rigid enough so that the module would not be twisted or bent by the fixture.
- Note (4) In the standard conditions, there is no function failure issue occurred. All the cosmetic specification is judged before reliability test.
- Note (5) Before cosmetic and function test, the product must have enough recovery time, at least 2 hours at room temperature.
- Note (6) Before cosmetic and function test, the product must have enough recovery time, at least 24 hours at room temperature.



#### 9. PACKAGING

#### 9.1 PACKING SPECIFICATIONS

- (1) 16pcs LCD modules / 1 Box
- (2) Box dimensions: 511 (L) X 420 (W) X 360 (H) mm
- (3) Weight: approximately 18Kg (16 modules per box)

#### 9.2 PACKING METHOD

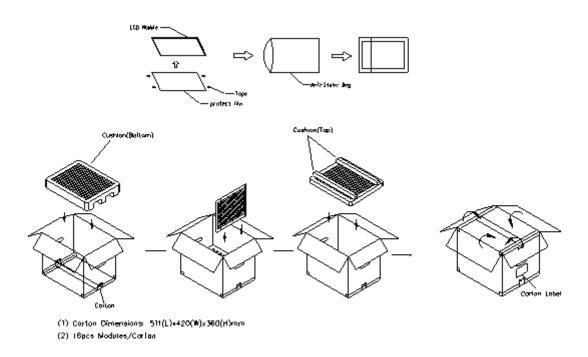


Figure. 9-1 Packing method

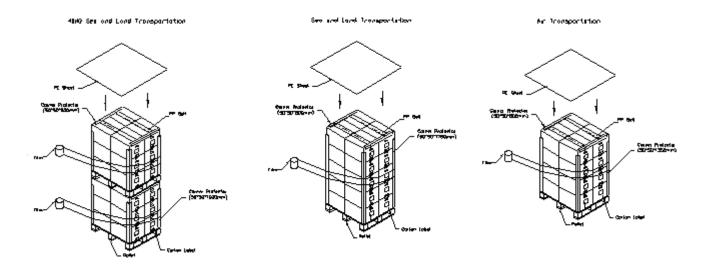


Figure. 9-2 Packing method



### 9.3 UN-PACKING METHOD

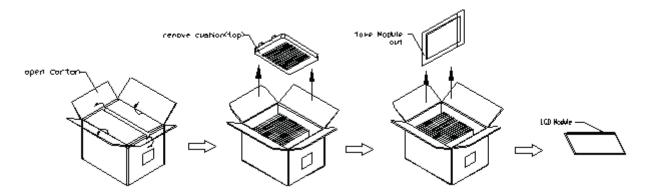


Figure. 9-3 UN-Packing method



#### 10. DEFINITION OF LABELS

#### **10.1 INX MODULE LABEL**

The barcode nameplate is pasted on each module as illustration, and its definitions are as following explanation.



(a)Model Name: G150XNE-L02

(b)\* \* \* \* : Factory ID

(c)Serial ID: XXXXXXXXXYMDXNNN

Serial

INX Internal Use
Year, Month, Date
INX Internal Use
Revision
INX Internal Use

Serial ID includes the information as below:

(a)Manufactured Date: Year: 1~9, for 2011~2019

Month: 1~9, A~C, for Jan. ~ Dec.

Day: 1~9, A~Y, for 1st to 31st, exclude I, O and U

(b)Revision Code: cover all the change

(c)Serial No.: Manufacturing sequence of product



#### 11. PRECAUTIONS

#### 11.1 ASSEMBLY AND HANDLING PRECAUTIONS

- (1)Do not apply rough force such as bending or twisting to the module during assembly.
- (2) To assemble or install module into user's system can be only in clean working areas. The dust and oil may cause electrical short or worsen the polarizer.
- (3) It's not permitted to have pressure or impulse on the module because the LCD panel and Backlight will be damaged.
- (4) Always follow the correct power sequence when LCD module is connecting and operating. This can prevent damage to the CMOS LSI chips during latch-up.
- (5) Do not pull the I/F connector in or out while the module is operating.
- (6) Do not disassemble the module.
- (7) Use a soft dry cloth without chemicals for cleaning, because the surface of polarizer is very soft and easily scratched.
- (8) It is dangerous that moisture come into or contacted the LCD module, because moisture may damage LCD module when it is operating.
- (9) High temperature or humidity may reduce the performance of module. Please store LCD module within the specified storage conditions.
- (10) When ambient temperature is lower than 10°C may reduce the display quality. For example, the response time will become slowly.
- (11) Do not keep same pattern in a long period of time. It may cause image sticking on LCD.

#### 11.2 SAFETY PRECAUTIONS

- (1) Do not disassemble the module or insert anything into the Backlight unit.
- (2) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, skin or clothes, it has to be washed away thoroughly with soap.
- (3) After the module's end of life, it is not harmful in case of normal operation and storage.



#### 12. MECHANICAL CHARACTERISTICS

